

Title (en)

ARRANGEMENT OF ELECTRICAL CONDUCTORS AND METHOD FOR MANUFACTURING AN ARRANGEMENT OF ELECTRICAL CONDUCTORS

Title (de)

ANORDNUNG ELEKTRISCHER LEITER UND VERFAHREN ZUR HERSTELLUNG EINER ANORDNUNG ELEKTRISCHER LEITER

Title (fr)

SYSTÈME DE CONDUCTEURS ÉLECTRIQUES ET PROCÉDÉ DE FABRICATION D'UN SYSTÈME DE CONDUCTEURS ÉLECTRIQUES

Publication

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Application

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Abstract (en)

[origin: CA2967703A1] The invention relates to an arrangement of electrical conductors comprising a conductor bundle having at least one individual electrical cable and at least one cooling line through which a cooling fluid is to flow. In order to thermally connect the conductor bundle to the at least one cooling line, one section of the at least one cooling line and the conductor bundle are embedded in a metal with a low melting temperature, wherein an insulating sheath of the at least one individual cable is embodied as plastic insulation, preferably as polyimide insulation or as polyester insulation. The invention also relates to a method for manufacturing such an arrangement.

IPC 8 full level

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